



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ018NE2LSI		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001021954						
<b>Package</b>		PG-TSDSON-8-26		<b>Weight*</b>		36.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.71	1.71	17110	17110
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5351	
wire	non noble metal	copper	7440-50-8	7.988	21.73	22.31	217265	222951
	noble metal	gold	7440-57-5	0.028	0.08	0.08	759	759
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1002	
	plastics	epoxy resin	-	1.897	5.16		51602	
	inorganic material	silicondioxide	60676-86-0	16.486	44.83	50.09	448386	500990
leadfinish	non noble metal	tin	7440-31-5	0.400	1.09	1.09	10885	10885
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	553	553
solder	noble metal	silver	7440-22-4	0.023	0.06		637	
	non noble metal	tin	7440-31-5	0.019	0.05		510	
	non noble metal	lead	7439-92-1	0.895	2.43	2.54	24330	25477
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2556	
	non noble metal	copper	7440-50-8	3.816	10.38	10.65	103784	106500
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2755	
	non noble metal	copper	7440-50-8	4.112	11.18	11.47	111848	114775
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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